MICRO-618 Soft Microsystems Processing and Devices

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Cursus	Sem.	Туре	Language of	English
Advanced Manufacturing		Obl.	teaching	English
Microsystems and Microelectronics		Obl.	Credits Session	2
			Exam	Oral
			Workload	60h
			Hours	28
			Courses	18
			TP	10
			Number of positions	16

Remark

Dates in 2018 : September 4 and 5 in Microcity & September 6 and 7 at EPFL

Summary

Amongst others, following topics will be covered during the course: - Soft Microsystems and Electronics - Electroactive polymers - Printed electronics and microsystems - Inkjet printing of polymers - Stretchable electronics - Mechanical reliability

Content

Introduction to Soft Microsystems and Electronics and conclusion:

- Introduction to the course objectives, content, program, lecturers, and evaluation
- Overview on soft microsystems and electronics devices and their processing: status, opportunities and challenges
- R&D and commercial status, examples of applications
- Concluding remarks and discussion

Electroactive polymers

Dielectric elastomer actuators (DEAs) are an emerging actuation technology which is inherent lightweight and compliant, enabling the development of unique and versatile devices with applications ranging from energy harvesting, to soft robotics, to tools for cellular biology, to haptics. The student will learn the basic physical principles of dielectric electroactive polymer actuators, the properties and processing of the elastomers and stretchable electrodes, the control and self-sensing methods, and an overview of different application areas and current research topics.

Printed electronics and microsystems

Some general sentences and some bullet points:

- Introduction to printed electronics: advantages and disavantages, comparison and complementarity with Si technology
- Materials: functional inks and substrates
- Additive and large area manufacturing: Printing and curing/sintering techniques
- Examples of printed electronics, optoelectronics, and sensing devices and systems
- Challenges and R&D perspectives

Inkjet printing of polymers

Inkjet Printing is a key enabling technology that goes well beyond the established paper printing. In recent years, novel areas have matured, where printing techniques find increasingly a pathway from R&D to industrial manufacturing. These areas not only include organic and printed opto-electronics, but also micro-optical, bio-medical, MEMS fabrication and packaging, and 3D rapid prototyping. This lecture will provide an introduction to ink-jet printing technologies in the various existing forms for applications in printed electronics, materials science and life-sciences:

History of inkjet printing and some examples of equipment

- Methods of producing mono-disperse micro drops: The theory behind drop-on-demand printing. Limits

- Printing of polymers, particularities

- Applications in manufacturing and engineering: SU-8, nano-composites, micro-optics, organic electronic materials,

bio-printing, tissue mimetics, etc.

Stretchable electronics

Stretchable electronics is a new evolution of microelectronics. Integrated circuits are no longer constrained to a flat, rigid carrier but rather incorporated within highly deformable carriers thus enabling the circuits to morph, adapting their shape by flexing, stretching or wrinkling.



In this lecture, we will review how materials and fabrication process inspired from those used in microelectronics and MEMS can be implemented to fabricate electronic devices and circuits on soft, skin-like substrates. Further, strategies for the mechanical design ensuring the electromechanical integrity of the stretchable circuits will be presented. Examples of microfabricated stretchable electronics designed for robotics and prosthetic applications will illustrate the lecture.

- Integrated circuits of arbitrary shapes
- a. Examples from academia
- b. First steps in industry
- Mechanical strains produced by shaping
- Materials and processes for stretchable electronics
- Electromechanical characterisation

Mechanical reliability

Soft microsystem and flexible electronic devices are often based on multilayer structures with a very high property contrast between material constituents, yet they should not distort during processing or crack upon bending or stretching. The lecture will present the key factors, which control the mechanical integrity of such structures. It will also provide the essential ingredients to design and produce reliable devices on soft substrates.

- Critical radius and critical strain
- Residual stresses and strains
- Cracking under